Renesas Electronics America Inc - R5F21368SNFP#V0 Datasheet

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Applications of "Embedded - Microcontrollers"

Details	
Product Status	Obsolete
Core Processor	R8C
Core Size	16-Bit
Speed	20MHz
Connectivity	I²C, LINbus, SIO, SSU, UART/USART
Peripherals	POR, PWM, Voltage Detect, WDT
Number of I/O	59
Program Memory Size	64KB (64K x 8)
Program Memory Type	FLASH
EEPROM Size	4K x 8
RAM Size	6K x 8
Voltage - Supply (Vcc/Vdd)	1.8V ~ 5.5V
Data Converters	A/D 12x10b
Oscillator Type	Internal
Operating Temperature	-20°C ~ 85°C (TA)
Mounting Type	Surface Mount
Package / Case	64-LQFP
Supplier Device Package	64-LFQFP (10x10)
Purchase URL	https://www.e-xfl.com/product-detail/renesas-electronics-america/r5f21368snfp-v0

Table 1.5 Pin Name Information by Pin Number (SSU/I²C, Timer RJ, and Timer RB2)

Port	Pin No.	SSU/I²C						Timer RJ		Timer RB2
		SCL_0	SDA_0	SSI_0	$\overline{SCS\_0}$	SSCK_0	SSO_0	TRJO_0	TRJIO_0	TRBO_0
P0_0	56									
P0_1	55									
P0_2	54									
P0_3	53									
P0_4	52									
P0_5	51									
P0_6	50									
P0_7	49									
P1_0	48									
P1_1	47									
P1_2	46									
P1_3	45									TRBO_0
P1_4	44									
P1_5	43								TRJIO_0	
P1_6	42									
P1_7	41									
P2_0	27									
P2_1	26									
P2_2	25									
P2_3	24									
P2_4	23									
P2_5	22									
P2_6	21									
P2_7	20									
P3_0	1							TRJO_0		
P3_1	29									
P3_2	64								TRJIO_0	
P3_3	19				$\overline{SCS\_0}$					
P3_4	18			SSI_0						
P3_5	17	SCL_0				SSCK_0				
P3_6	28									
P3_7	16		SDA_0				SSO_0			
P4_2	2									
P4_3	4									
P4_4	5									
P4_5	40									
P4_6	9									
P4_7	7									
P5_0	15									
P5_1	14									
P5_2	13									
P5_3	12									
P5_4	11									
P5_6	63									
P5_7	62									
P6_0	61									
P6_1	60									
P6_2	59									
P6_3	58									
P6_4	57									
P6_5	39									
P6_6	38									
P6_7	37									
P8_0	36									
P8_1	35									
P8_2	34									
P8_3	33									
P8_4	32									
P8_5	31									
P8_6	30									

Table 1.6 Pin Name Information by Pin Number (Timer RC, Timer RE2, and Others)

Port	Pin No.	Timer RC						Timer RE2	Others		
		TRCCLK_0	TRCIOA_0	TRCIOB_0	TRCIOC_0	TRCIOD_0	TRCTRG_0	TMRE2O			
P0_0	56		TRCIOA_0				TRCTRG_0		AN7		
P0_1	55		TRCIOA_0				TRCTRG_0		AN6		
P0_2	54		TRCIOA_0				TRCTRG_0		AN5		
P0_3	53			TRCIOB_0					AN4		
P0_4	52			TRCIOB_0				TMRE2O	AN3		
P0_5	51			TRCIOB_0					AN2		
P0_6	50					TRCIOD_0			AN1		
P0_7	49				TRCIOC_0				AN0		
P1_0	48					TRCIOD_0			AN8	$\overline{KI0}$	
P1_1	47		TRCIOA_0				TRCTRG_0		AN9	$\overline{KI1}$	
P1_2	46			TRCIOB_0					AN10	$\overline{KI2}$	
P1_3	45				TRCIOC_0				AN11	$\overline{KI3}$	
P1_4	44	TRCCLK_0									
P1_5	43										
P1_6	42								IVREF1		CH00
P1_7	41								IVCMP1		CH01
P2_0	27			TRCIOB_0							CH16
P2_1	26				TRCIOC_0						CH17
P2_2	25					TRCIOD_0					CH18
P2_3	24										CH19
P2_4	23										CH20
P2_5	22										CH21
P2_6	21										CH22
P2_7	20										CH23
P3_0	1										CH24
P3_1	29										CH10
P3_2	64										CH25
P3_3	19	TRCCLK_0							IVCMP3		
P3_4	18				TRCIOC_0				IVREF3		
P3_5	17					TRCIOD_0					
P3_6	28										CH11
P3_7	16										
P4_2	2								VREF		
P4_3	4								XCIN		
P4_4	5								XCOUT		
P4_5	40								$\overline{ADTRG}$		CH02
P4_6	9								XIN		
P4_7	7								XOUT		
P5_0	15	TRCCLK_0									
P5_1	14		TRCIOA_0				TRCTRG_0				
P5_2	13			TRCIOB_0							
P5_3	12				TRCIOC_0						
P5_4	11					TRCIOD_0					
P5_6	63										CH27
P5_7	62										CH28
P6_0	61							TMRE2O			CH31
P6_1	60										CH32
P6_2	59										CH33
P6_3	58										CH34
P6_4	57										CH35
P6_5	39			TRCIOB_0							CH03
P6_6	38				TRCIOC_0						CH04
P6_7	37					TRCIOD_0					CH05
P8_0	36										CH06
P8_1	35										CH07
P8_2	34										CHxA0
P8_3	33										CHxA1
P8_4	32										CHxB
P8_5	31										CHxC
P8_6	30										CH08

2.1 Data Registers (R0, R1, R2, and R3)

R0 is a 16-bit register for transfer, arithmetic, and logic operations. The same applies to R1 through R3. R0 can be split into high-order (R0H) and low-order (R0L) registers to be used separately as 8-bit data registers. The same applies to R1H and R1L. R2 can be combined with R0 and used as a 32-bit data register (R2R0). Similarly, R3 and R1 can be used as a 32-bit data register.

2.2 Address Registers (A0 and A1)

A0 is a 16-bit register for address register indirect addressing and address register relative addressing. It is also used for transfer, arithmetic, and logic operations. A1 functions in the same manner as A0. A1 can be combined with A0 and used as a 32-bit address register (A1A0).

2.3 Frame Base Register (FB)

FB is a 16-bit register used for FB relative addressing.

2.4 Interrupt Table Register (INTB)

INTB is a 20-bit register that indicates the start address of a relocatable interrupt vector table.

2.5 Program Counter (PC)

PC is a 20-bit register that indicates the address of the next instruction to be executed.

2.6 User Stack Pointer (USP) and Interrupt Stack Pointer (ISP)

The stack pointers (SP), USP and ISP, are each 16 bits wide. The U flag of the FLG register is used to switch between USP and ISP.

2.7 Static Base Register (SB)

SB is a 16-bit register used for SB relative addressing.

2.8 Flag Register (FLG)

FLG is an 11-bit register that indicates the CPU state.

2.8.1 Carry Flag (C)

The C flag retains carry, borrow, or shift-out bits that have been generated in the arithmetic and logic unit.

2.8.2 Debug Flag (D)

The D flag is for debugging only. It must only be set to 0.

2.8.3 Zero Flag (Z)

The Z flag is set to 1 when an arithmetic operation results in 0. Otherwise it is set to 0.

2.8.4 Sign Flag (S)

The S flag is set to 1 when an arithmetic operation results in a negative value. Otherwise it is set to 0.

2.8.5 Register Bank Select Flag (B)

Register bank 0 is selected when the B flag is 0. Register bank 1 is selected when this flag is 1.

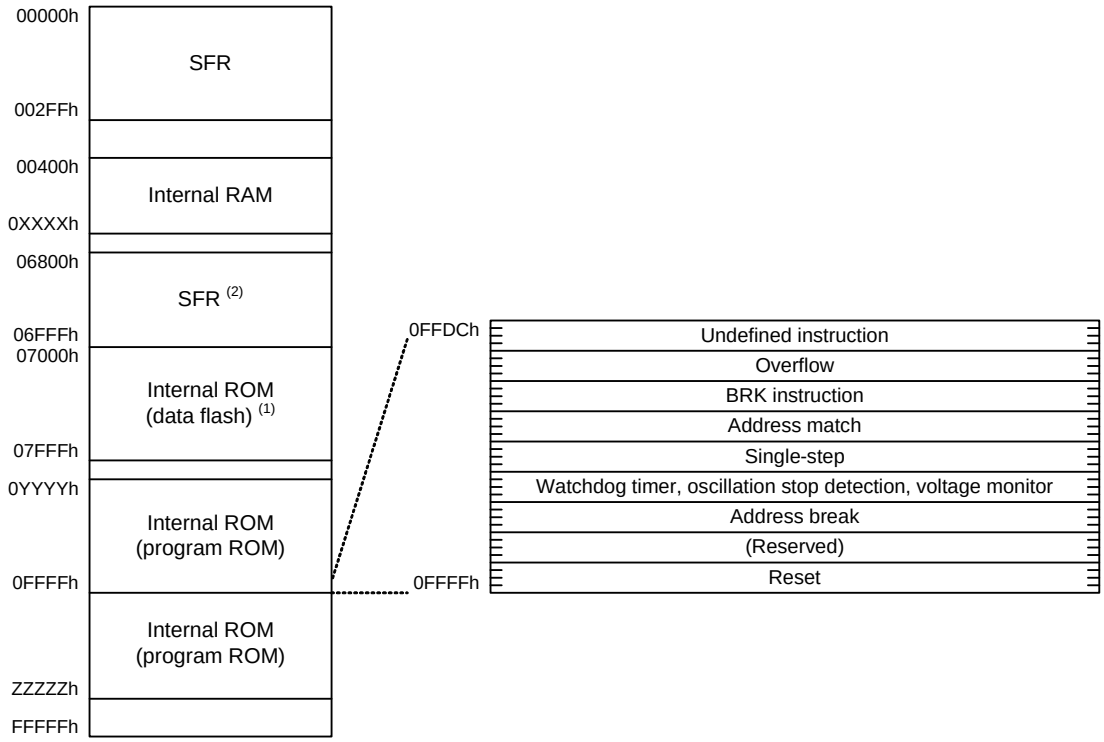
2.8.6 Overflow Flag (O)

The O flag is set to 1 when an operation results in an overflow. Otherwise it is set to 0.

3. Address Space

3.1 Memory Map

Figure 3.1 shows the Memory Map. The R8C/36T-A Group has a 1-Mbyte address space from addresses 00000h to FFFFFh. Up to 32 Kbytes of the internal ROM (program ROM) is allocated at lower addresses, beginning with address 0FFFFh. The area in excess of 32 Kbytes is allocated at higher addresses, beginning with address 10000h. For example, a 64-Kbyte internal ROM is allocated at addresses 08000h to 17FFFh.
The fixed interrupt vector table is allocated at addresses 0FFDCh to 0FFFFh. The start address of each interrupt routine is stored here.
The internal ROM (data flash) is allocated at addresses 07000h to 07FFFh.
The internal RAM is allocated at higher addresses, beginning with address 00400h. For example, a 6-Kbyte internal RAM is allocated at addresses 00400h to 01BFFh. The internal RAM is used not only for data storage but also as a stack area when a subroutine is called or when an interrupt request is acknowledged.
Special function registers (SFRs) are allocated at addresses 00000h to 02FFFh and addresses 06800h to 06FFFh. Peripheral function control registers are allocated here. All unallocated locations within the SFRs are reserved and cannot be accessed by users.



Notes:
1. Data flash indicates block A (1 Kbyte), block B (1 Kbyte), block C (1 Kbyte), and block D (1 Kbyte).
2. Addresses 06800h to 06FFFh are used for the ELC, DTC, and TSCU SFR areas.
3. The blank areas are reserved. No access is allowed.

Part Number	Internal ROM			Internal RAM	
	Capacity	Address 0YYYYh	Address ZZZZZh	Capacity	Address 0XXXXh
R5F21368SNFP/FA, R5F21368SDFP/FA	64 Kbytes	08000h	17FFFh	6 Kbytes	01BFFh
R5F21368SNFP/FA, R5F21368SDFP/FA	96 Kbytes	08000h	1FFFFh	8 Kbytes	023FFh
R5F21368SNFP/FA, R5F21368SDFP/FA	128 Kbytes	08000h	27FFFh	10 Kbytes	02BFFh

Figure 3.1 Memory Map

Table 3.2 SFR Information (2) (1)

Address	Symbol	Register Name	After Reset	Remarks
0003Ah	VW2C	Voltage Monitor 2 Circuit Control Register	10001010b	
0003Bh				
0003Ch				
0003Dh				
0003Eh				
0003Fh				
00040h				
00041h	FMRDYIC	Interrupt Control Register	00h	
00042h				
00043h				
00044h				
00045h				
00046h	INT4IC	Interrupt Control Register	00h	
00047h	TRCIC_0	Interrupt Control Register	00h	
00048h				
00049h				
0004Ah	TRE2IC	Interrupt Control Register	00h	
0004Bh	U2TIC	Interrupt Control Register	00h	
0004Ch	U2RIC	Interrupt Control Register	00h	
0004Dh	KUPIC	Interrupt Control Register	00h	
0004Eh	ADIC	Interrupt Control Register	00h	
0004Fh	SSUIC_0/IICIC_0	Interrupt Control Register	00h	
00050h				
00051h	U0TIC_0	Interrupt Control Register	00h	
00052h	U0RIC_0	Interrupt Control Register	00h	
00053h	U0TIC_1	Interrupt Control Register	00h	
00054h	U0RIC_1	Interrupt Control Register	00h	
00055h	INT2IC	Interrupt Control Register	00h	
00056h	TRJIC_0	Interrupt Control Register	00h	
00057h				
00058h	TRB2IC_0	Interrupt Control Register	00h	
00059h	INT1IC	Interrupt Control Register	00h	
0005Ah	INT3IC	Interrupt Control Register	00h	
0005Bh				
0005Ch				
0005Dh	INT0IC	Interrupt Control Register	00h	
0005Eh	U2BCNIC	Interrupt Control Register	00h	
0005Fh				
00060h				
00061h				
00062h				
00063h				
00064h				
00065h				
00066h				
00067h				
00068h				
00069h				
0006Ah				
0006Bh				
0006Ch				
0006Dh				
0006Eh				
0006Fh				
00070h				
00071h				
00072h	VCMP1IC	Interrupt Control Register	00h	
00073h	VCMP2IC	Interrupt Control Register	00h	
00074h				
00075h	TSCUIC	Interrupt Control Register	00h	
00076h				
00077h				
00078h				
00079h				

Note:
1. The blank areas are reserved. No access is allowed.

Table 3.3 SFR Information (3) (1)

Address	Symbol	Register Name	After Reset	Remarks
0007Ah				
0007Bh				
0007Ch				
0007Dh				
0007Eh				
0007Fh				
00080h	U0MR_0	UART0_0 Transmit/Receive Mode Register	00h	
00081h	U0BRG_0	UART0_0 Bit Rate Register	XXh	
00082h	U0TB_0	UART0_0 Transmit Buffer Register	XXh	
00083h			XXh	
00084h	U0C0_0	UART0_0 Transmit/Receive Control Register 0	00001000b	
00085h	U0C1_0	UART0_0 Transmit/Receive Control Register 1	00000010b	
00086h	U0RB_0	UART0_0 Receive Buffer Register	XXXXh	
00087h				
00088h	U0IR_0	UART0_0 Interrupt Flag and Enable Register	00h	
00089h				
0008Ah				
0008Bh				
0008Ch	LINCR2_0	LIN_0 Special Function Register	00h	
0008Dh				
0008Eh	LINCT_0	LIN_0 Control Register	00h	
0008Fh	LINST_0	LIN_0 Status Register	00h	
00090h	U0MR_1	UART0_1 Transmit/Receive Mode Register	00h	
00091h	U0BRG_1	UART0_1 Bit Rate Register	XXh	
00092h	U0TB_1	UART0_1 Transmit Buffer Register	XXh	
00093h			XXh	
00094h	U0C0_1	UART0_1 Transmit/Receive Control Register 0	00001000b	
00095h	U0C1_1	UART0_1 Transmit/Receive Control Register 1	00000010b	
00096h	U0RB_1	UART0_1 Receive Buffer Register	XXXXh	
00097h				
00098h	U0IR_1	UART0_1 Interrupt Flag and Enable Register	00h	
00099h				
0009Ah				
0009Bh				
0009Ch				
0009Dh				
0009Eh				
0009Fh				
000A0h				
000A1h				
000A2h				
000A3h				
000A4h				
000A5h				
000A8h				
000A9h				
000AAh				
000ABh				
000ACh				
000ADh				
000AEh				
000AFh				
000B0h				
000B1h				
000B4h				
000B5h				
000B8h				
000B9h				

X: Undefined

Note:

1. The blank areas are reserved. No access is allowed.

Table 3.6 SFR Information (6) (1)

Address	Symbol	Register Name	After Reset	Remarks
0013Ah	TRCGRA_0	Timer RC_0 General Register A	FFFFh	
0013Bh				
0013Ch	TRCGRB_0	Timer RC_0 General Register B	FFFFh	
0013Dh				
0013Eh	TRCGRC_0	Timer RC_0 General Register C	FFFFh	
0013Fh				
00140h	TRCGRD_0	Timer RC_0 General Register D	FFFFh	
00141h				
00142h	TRCMR_0	Timer RC_0 Mode Register	01001000b	
00143h	TRCCR1_0	Timer RC_0 Control Register 1	00h	
00144h	TRCIER_0	Timer RC_0 Interrupt Enable Register	01110000b	
00145h	TRCSR_0	Timer RC_0 Status Register	01110000b	
00146h	TRCIOR0_0	Timer RC_0 I/O Control Register 0	10001000b	
00147h	TRCIOR1_0	Timer RC_0 I/O Control Register 1	10001000b	
00148h	TRCCR2_0	Timer RC_0 Control Register 2	00011000b	
00149h	TRCDF_0	Timer RC_0 Digital Filter Function Select Register	00h	
0014Ah	TRCOER_0	Timer RC_0 Output Enable Register	01111111b	
0014Bh	TRCADCR_0	Timer RC_0 A/D Conversion Trigger Control Register	11110000b	
0014Ch	TRCOPR_0	Timer RC_0 Output Waveform Manipulation Register	00h	
0014Dh	TRCELCCR_0	Timer RC_0 ELC Cooperation Control Register	00h	
0014Eh				
0014Fh				
00150h				
00151h				
00152h				
00153h				
00154h				
00155h				
00156h				
00157h				
00158h				
00159h				
0015Ah				
0015Bh				
0015Ch				
0015Dh				
0015Eh				
0015Fh				
00160h				
00161h				
00162h				
00163h				
00164h				
00165h				
00166h				
00167h				
00168h				
00169h				
0016Ah				
0016Bh				
0016Ch				
0016Dh				
0016Eh				
0016Fh				
00170h	TRESEC	Timer RE2 Counter Data Register Timer RE2 Second Data Register	00h	
00171h	TREMIN	Timer RE2 Compare Data Register Timer RE2 Minute Data Register	00h	
00172h	TREHR	Timer RE2 Hour Data Register	00h	
00173h	TREWK	Timer RE2 Day-of-the-Week Data Register	00h	
00174h	TREDY	Timer RE2 Day Data Register	00000001b	
00175h	TREMON	Timer RE2 Month Data Register	00000001b	
00176h	TREYR	Timer RE2 Year Data Register	00h	
00177h	TRECR	Timer RE2 Control Register	00000100b	
00178h	TRECSR	Timer RE2 Count Source Select Register	00001000b	
00179h	TREADJ	Timer RE2 Clock Error Correction Register	00h	

Note:
1. The blank areas are reserved. No access is allowed.

Table 3.7 SFR Information (7) (1)

Address	Symbol	Register Name	After Reset	Remarks
0017Ah	TREIFR	Timer RE2 Interrupt Flag Register	00h	
0017Bh	TREIER	Timer RE2 Interrupt Enable Register	00h	
0017Ch	TREAMN	Timer RE2 Alarm Minute Register	00h	
0017Dh	TREAHR	Timer RE2 Alarm Hour Register	00h	
0017Eh	TREAWK	Timer RE2 Alarm Day-of-the-Week Register	00h	
0017Fh	TREPRC	Timer RE2 Protect Register	00h	
00180h to 001FFh				
00200h	AD0	A/D Register 0	00h	
00201h			00h	
00202h	AD1	A/D Register 1	00h	
00203h			00h	
00204h	AD2	A/D Register 2	00h	
00205h			00h	
00206h	AD3	A/D Register 3	00h	
00207h			00h	
00208h	AD4	A/D Register 4	00h	
00209h			00h	
0020Ah	AD5	A/D Register 5	00h	
0020Bh			00h	
0020Ch	AD6	A/D Register 6	00h	
0020Dh			00h	
0020Eh	AD7	A/D Register 7	00h	
0020Fh			00h	
00210h				
00211h				
00212h				
00213h				
00214h	ADMOD	A/D Mode Register	00h	
00215h	ADINSEL	A/D Input Select Register	11000000b	
00216h	ADCON0	A/D Control Register 0	00h	
00217h	ADCON1	A/D Control Register 1	00h	
00218h				
00219h				
0021Ah				
0021Bh				
0021Ch				
0021Dh				
0021Eh				
0021Fh				
00220h				
00221h				
00222h				
00223h				
00224h				
00225h				
00226h				
00227h				
00228h	INTCMP	Comparator B Control Register 0	00h	
00229h				
0022Ah				
0022Bh				
0022Ch				
0022Dh				
0022Eh				
0022Fh				
00230h	INTEN	External Input Enable Register 0	00h	
00231h	INTEN1	External Input Enable Register 1	00h	
00232h	INTF	INT Input Filter Select Register 0	00h	
00233h	INTF1	INT Input Filter Select Register 1	00h	
00234h	INTPOL	INT Input Polarity Switch Register	00h	
00235h				
00236h	KIEN	Key Input Interrupt Enable Register	00h	
00237h				
00238h	MSTCR0	Module Standby Control Register 0	00h	
00239h	MSTCR1	Module Standby Control Register 1	00h	

Note:
1. The blank areas are reserved. No access is allowed.

Table 4.6 Flash Memory (Data flash Block A to Block D) Characteristics (Vcc = 2.7 V to 5.5 V, Topr = –20°C to 85°C (N version)/–40°C to 85°C (D version), unless otherwise specified)

Symbol	Parameter	Conditions	Standard			Unit
			Min.	Typ.	Max.	
—	Program/erase endurance (1)		10,000 (2)	—	—	times
—	Byte program time (Program and erase endurance ≤ 1,000 times)		—	160	950	µs
—	Byte program time (Program and erase endurance > 1,000 times)		—	300	950	µs
—	Block erase time (Program and erase endurance ≤ 1,000 times)		—	0.2	1	s
—	Block erase time (Program and erase endurance > 1,000 times)		—	0.3	1	s
$t_{d(SR-SUS)}$	Time delay from suspend request until suspend		—	—	3 + CPU clock × 3 cycles	ms
—	Interval from erase start/restart until following suspend request		0	—	—	µs
—	Time from suspend until erase restart		—	—	30 + CPU clock × 1 cycle	µs
$t_{d(CMDRST-READY)}$	Time from when command is forcibly terminated until reading is enabled		—	—	30 + CPU clock × 1 cycle	µs
—	Program, erase voltage		2.7	—	5.5	V
—	Read voltage		1.8	—	5.5	V
—	Program, erase temperature		–20 (N ver.) –40 (D ver.)	—	85	°C
—	Data hold time (6)	Ambient temperature = 55°C (7)	20	—	—	year

Notes:
1. Definition of programming/erasure endurance
   The programming and erasure endurance is defined on a per-block basis.
   If the programming and erasure endurance is n (n = 100, 1,000 or 10,000), each block can be erased n times. For example, if 1,024 1-byte writes are performed to different addresses in block A, a 1 Kbyte block, and then the block is erased, the programming/erasure endurance still stands at one.
   However, the same address must not be programmed more than once per erase operation (overwriting prohibited).
2. Endurance to guarantee all electrical characteristics after program and erase. (1 to Min. value can be guaranteed).
3. In a system that executes multiple programming operations, the actual erasure count can be reduced by writing to sequential addresses in turn so that as much of the block as possible is used up before performing an erase operation. For example, when programming groups of 16 bytes, the effective number of rewrites can be minimized by programming up to 128 groups before erasing them all in one operation. In addition, averaging the erasure endurance between blocks A to D can further reduce the actual erasure endurance. It is also advisable to retain data on the erasure endurance of each block and limit the number of erase operations to a certain number.
4. If an error occurs during block erase, attempt to execute the clear status register command, then execute the block erase command at least three times until the erase error does not occur.
5. Customers desiring program/erase failure rate information should contact their Renesas technical support representative.
6. The data hold time includes time that the power supply is off or the clock is not supplied.
7. The data hold time includes 7,000 hours under an environment of ambient temperature 85°C.

Table 4.8 Voltage Detection 1 Circuit Characteristics (Measurement conditions: Vcc = 1.8 V to 5.5 V, Topr = –20°C to 85°C (N version)/ –40°C to 85°C (D version))

Symbol	Parameter	Conditions	Standard			Unit
			Min.	Typ.	Max.	
V_{det1}	Voltage detection level Vdet1_0 (1)	When Vcc falls	2.00	2.20	2.40	V
	Voltage detection level Vdet1_1 (1)	When Vcc falls	2.15	2.35	2.55	V
	Voltage detection level Vdet1_2 (1)	When Vcc falls	2.30	2.50	2.70	V
	Voltage detection level Vdet1_3 (1)	When Vcc falls	2.45	2.65	2.85	V
	Voltage detection level Vdet1_4 (1)	When Vcc falls	2.60	2.80	3.00	V
	Voltage detection level Vdet1_5 (1)	When Vcc falls	2.75	2.95	3.15	V
	Voltage detection level Vdet1_6 (1)	When Vcc falls	2.80	3.10	3.40	V
	Voltage detection level Vdet1_7 (1)	When Vcc falls	2.95	3.25	3.55	V
	Voltage detection level Vdet1_8 (1)	When Vcc falls	3.10	3.40	3.70	V
	Voltage detection level Vdet1_9 (1)	When Vcc falls	3.25	3.55	3.85	V
	Voltage detection level Vdet1_A (1)	When Vcc falls	3.40	3.70	4.00	V
	Voltage detection level Vdet1_B (1)	When Vcc falls	3.55	3.85	4.15	V
	Voltage detection level Vdet1_C (1)	When Vcc falls	3.70	4.00	4.30	V
	Voltage detection level Vdet1_D (1)	When Vcc falls	3.85	4.15	4.45	V
	Voltage detection level Vdet1_E (1)	When Vcc falls	4.00	4.30	4.60	V
	Voltage detection level Vdet1_F (1)	When Vcc falls	4.15	4.45	4.75	V
—	Hysteresis width at the rising of Vcc in voltage detection 1 circuit	Vdet1_0 to Vdet1_5 selected	—	0.07	—	V
		Vdet1_6 to Vdet1_F selected	—	0.10	—	V
—	Voltage detection 1 circuit response time (2)	At the falling of Vcc from 5 V to (Vdet1 – 0.1) V	—	60	150	µs
—	Voltage detection circuit self power consumption	VCA26 = 1, Vcc = 5.0 V	—	1.7	—	µA
$t_{d(E-A)}$	Waiting time until voltage detection circuit operation starts (3)		—	—	100	µs

Notes:
1. Select the voltage detection level with bits VD1S0 to VD1S3 in the VD1LS register.
2. Time until the voltage monitor 1 interrupt request is generated after the voltage passes V_{det1}.
3. Necessary time until the voltage detection circuit operates when setting to 1 again after setting the VCA26 bit in the VCA2 register to 0.

Table 4.9 Voltage Detection 2 Circuit Characteristics (Measurement conditions: Vcc = 1.8 V to 5.5 V, Topr = –20°C to 85°C (N version)/ –40°C to 85°C (D version))

Symbol	Parameter	Conditions	Standard			Unit
			Min.	Typ.	Max.	
V_{det2}	Voltage detection level Vdet2_0	When Vcc falls	3.70	4.00	4.30	V
—	Hysteresis width at the rising of Vcc in voltage detection 2 circuit		—	0.1	—	µs
—	Voltage detection 2 circuit response time (1)	At the falling of Vcc from 5 V to (Vdet2_0 – 0.1) V	—	20	150	µs
—	Voltage detection circuit self power consumption	VCA27 = 1, Vcc = 5.0 V	—	1.7	—	µA
$t_{d(E-A)}$	Waiting time until voltage detection circuit operation starts (2)		—	—	100	µs

Notes:
1. Time until the voltage monitor 2 interrupt request is generated after the voltage passes V_{det2}.
2. Necessary time until the voltage detection circuit operates when setting to 1 again after setting the VCA26 bit in the VCA2 register to 0.

4.4 DC Characteristics

Table 4.14 DC Characteristics (1) [4.2 V ≤ Vcc ≤ 5.5 V] (Measurement conditions: Vcc = 1.8 V to 5.5 V, Topr = –20°C to 85°C (N version)/ –40°C to 85°C (D version))

Symbol	Parameter		Conditions		Standard			Unit
					Min.	Typ.	Max.	
V_{OH}	Output high voltage	Other than XOUT	Drive capacity is high	I_{OH} = –20 mA	Vcc – 2.0	—	Vcc	V
			Drive capacity is low	I_{OH} = –5 mA	Vcc – 2.0	—	Vcc	V
				I_{OH} = –200 µA	Vcc – 0.3	—	Vcc	V
		XOUT		I_{OH} = –200 µA	1.0	—	Vcc	V
V_{OL}	Output low voltage	Other than XOUT	Drive capacity is high	I_{OL}= 20 mA	—	—	2.0	V
			Drive capacity is low	I_{OL} = 5 mA	—	—	2.0	V
				I_{OL} = 200 µA	—	—	0.45	V
		XOUT		I_{OL} = 200 µA	—	—	0.5	V
V_{T+}-V_{T-}	Hysteresis	$\overline{INT0}$ to $\overline{INT4}$, $\overline{KI0}$ to $\overline{KI3}$, TRJIO_0, TRCCLK_0, TRCTRG_0, TRCIOA_0, TRCIOB_0, TRCIOC_0, TRCIOD_0, CLK_0, CLK_1, $\overline{RXD\_0}$, RXD_1, $\overline{CTS2}$, SCL2, SDA2, CLK2, RXD2, $\underline{SCL\_0}$, SDA_0, SSI_0, $\overline{SCS\_0}$, SSCK_0, SSO_0			0.1	1.2	—	V
		$\overline{RESET}$	Vcc = 5.0 V		0.1	1.2	—	V
I_{IH}	Input high current		V_I = 5.0 V		—	—	1.0	µA
I_{IL}	Input low current		V_I = 0 V		—	—	–1.0	µA
R_{PULLUP}	Pull-up resistance		V_I = 0 V		25	50	100	kΩ
R_{fXIN}	Feedback resistance	XIN			—	0.3	—	MΩ
R_{fXCIN}	Feedback resistance	XCIN			—	8	—	MΩ
V_{RAM}	RAM hold voltage		During stop mode		1.8	—	—	V

Table 4.15 DC Characteristics (2) [3.3 V ≤ Vcc ≤ 5.5 V] (Topr = –20°C to 85°C (N version)/–40°C to 85°C (D version), unless otherwise specified)

Symbol	Parameter	Conditions								Standard (4)			Unit
			Oscillation		On-Chip Oscillator		CPU Clock	Low-Power-Consumption Setting	Other	Min.	Typ.	Max.	
			XIN (2)	XCIN	High-Speed	Low-Speed							
Icc	Power supply current (1)	High-speed clock mode	20 MHz	Off	Off	125 kHz	No division	—		—	6.5	15	mA
			16 MHz	Off	Off	125 kHz	No division	—		—	5.3	12.5	mA
			10 MHz	Off	Off	125 kHz	No division	—		—	3.6	—	mA
			20 MHz	Off	Off	125 kHz	Divide-by-8	—		—	3.0	—	mA
			16 MHz	Off	Off	125 kHz	Divide-by-8	—		—	2.2	—	mA
			10 MHz	Off	Off	125 kHz	Divide-by-8	—		—	1.5	—	mA
		High-speed on-chip oscillator mode	Off	Off	20 MHz (3)	125 kHz	No division	—		—	7.0	15	mA
			Off	Off	20 MHz (3)	125 kHz	Divide-by-8	—		—	3.0	—	mA
			Off	Off	4 MHz (3)	125 kHz	Divide-by-16	MSTIIC = 1 MSTTRC = 1		—	1	—	mA
		Low-speed on-chip oscillator mode	Off	Off	Off	125 kHz	Divide-by-8	FMR27 = 1 SVC0 = 0		—	90	400	µA
		Low-speed clock mode	Off	32 kHz	Off	Off	—	FMR27 = 1 SVC0 = 0		—	85	400	µA
			Off	32 kHz	Off	Off	—	FMSTP = 1 SVC0 = 0	Program operation on RAM Flash memory off	—	47	—	µA
		Wait mode	Off	Off	Off	125 kHz	—	VCA27 = 0 VCA26 = 0 VCA25 = 0 SVC0 = 1	While a WAIT instruction is executed Peripheral clock operation	—	15	100	µA
			Off	Off	Off	125 kHz	—	VCA27 = 0 VCA26 = 0 VCA25 = 0 SVC0 = 1	While a WAIT instruction is executed Peripheral clock off	—	4	90	µA
			Off	32 kHz	Off	Off	—	VCA27 = 0 VCA26 = 0 VCA25 = 0 SVC0 = 1	While a WAIT instruction is executed Peripheral clock off	—	3.5	—	µA
		Stop mode	Off	Off	Off	Off	—	VCA27 = 0 VCA26 = 0 VCA25 = 0 CM10 = 1	Topr = 25°C Peripheral clock off	—	2.2	6.0	µA
			Off	Off	Off	Off	—	VCA27 = 0 VCA26 = 0 VCA25 = 0 CM10 = 1	Topr = 85°C Peripheral clock off	—	30	—	µA

Notes:
1. Vcc = 3.3 V to 5.5 V, single-chip mode, output pins are open, and other pins are Vss.
2. XIN is set to square wave input.
3. fHOCO-F
4. The typical value (Typ.) indicates the current value when the CPU and the memory operate.
   The maximum value (Max.) indicates the current value when the CPU, the memory, and the peripheral functions operate and the flash memory is programmed/erased.

Table 4.17 DC Characteristics (4) [2.7 V ≤ Vcc < 3.3 V] (Topr = –20°C to 85°C (N version)/–40°C to 85°C (D version), unless otherwise specified))

Symbol	Parameter	Conditions								Standard (4)			Unit
			Oscillation		On-Chip Oscillator		CPU Clock	Low-Power-Consumption Setting	Other	Min.	Typ.	Max.	
			XIN (2)	XCIN	High-Speed	Low-Speed							
Icc	Power supply current (1)	High-speed clock mode	10 MHz	Off	Off	125 kHz	No division	—		—	3.5	10	mA
			10 MHz	Off	Off	125 kHz	Divide-by-8	—		—	1.5	7.5	mA
		High-speed on-chip oscillator mode	Off	Off	20 MHz (3)	125 kHz	No division	—		—	7.0	15	mA
			Off	Off	20 MHz (3)	125 kHz	Divide-by-8	—		—	3.0	—	mA
			Off	Off	10 MHz (3)	125 kHz	No division	—		—	4.0	—	mA
			Off	Off	10 MHz (3)	125 kHz	Divide-by-8	—		—	1.5	—	mA
			Off	Off	4 MHz (3)	125 kHz	Divide-by-16	MSTIIC = 1 MSTTRC = 1		—	1	—	mA
		Low-speed on-chip oscillator mode	Off	Off	Off	125 kHz	Divide-by-8	FMR27 = 1 SVC0 = 0		—	90	390	µA
		Low-speed clock mode	Off	32 kHz	Off	Off	No division	FMR27 = 1 SVC0 = 0		—	80	400	µA
			Off	32 kHz	Off	Off	No division	FMSTP = 1 SVC0 = 0	Program operation on RAM Flash memory off	—	40	—	µA
		Wait mode	Off	Off	Off	125 kHz	—	VCA27 = 0 VCA26 = 0 VCA25 = 0 SVC0 = 1	While a WAIT instruction is executed Peripheral clock operation	—	15	90	µA
			Off	Off	Off	125 kHz	—	VCA27 = 0 VCA26 = 0 VCA25 = 0 SVC0 = 1	While a WAIT instruction is executed Peripheral clock off	—	4	80	µA
			Off	32 kHz	Off	Off	—	VCA27 = 0 VCA26 = 0 VCA25 = 0 SVC0 = 1	While a WAIT instruction is executed Peripheral clock off	—	3.5	—	µA
		Stop mode	Off	Off	Off	Off	—	VCA27 = 0 VCA26 = 0 VCA25 = 0 CM10 = 1	Topr = 25°C Peripheral clock off	—	2.2	6.0	µA
			Off	Off	Off	Off	—	VCA27 = 0 VCA26 = 0 VCA25 = 0 CM10 = 1	Topr = 85°C Peripheral clock off	—	30	—	µA

Notes:
1. Vcc = 2.7 V to 3.3 V, single-chip mode, output pins are open, and other pins are Vss.
2. XIN is set to square wave input.
3. fHOCO-F
4. The typical value (Typ.) indicates the current value when the CPU and the memory operate.
   The maximum value (Max.) indicates the current value when the CPU, the memory, and the peripheral functions operate and the flash memory is programmed/erased.

Table 4.19 DC Characteristics (6) [1.8 V ≤ Vcc < 2.7 V] (Topr = –20°C to 85°C (N version)/–40°C to 85°C (D version), unless otherwise specified)

Symbol	Parameter	Conditions								Standard (4)			Unit
			Oscillation		On-Chip Oscillator		CPU Clock	Low-Power-Consumption Setting	Other	Min.	Typ.	Max.	
			XIN (2)	XCIN	High-Speed	Low-Speed							
Icc	Power supply current (1)	High-speed clock mode	5 MHz	Off	Off	125 kHz	No division	—		—	2.2	—	mA
			5 MHz	Off	Off	125 kHz	Divide-by-8	—		—	0.8	—	mA
		High-speed on-chip oscillator mode	Off	Off	5 MHz (3)	125 kHz	No division	—		—	2.5	10	mA
			Off	Off	5 MHz (3)	125 kHz	Divide-by-8	—		—	1.7	—	mA
			Off	Off	4 MHz (3)	125 kHz	Divide-by-16	MSTIIC = 1 MSTTRC = 1		—	1	—	mA
		Low-speed on-chip oscillator mode	Off	Off	Off	125 kHz	Divide-by-8	FMR27 = 1 SVC0 = 0		—	90	300	µA
		Low-speed clock mode	Off	32 kHz	Off	Off	No division	FMR27 = 1 SVC0 = 0		—	80	350	µA
		Wait mode	Off	Off	Off	125 kHz	—	VCA27 = 0 VCA26 = 0 VCA25 = 0 SVC0 = 1	While a WAIT instruction is executed Peripheral clock operation	—	15	90	µA
			Off	Off	Off	125 kHz	—	VCA27 = 0 VCA26 = 0 VCA25 = 0 SVC0 = 1	While a WAIT instruction is executed Peripheral clock off	—	4	80	µA
			Off	32 kHz	Off	Off	—	VCA27 = 0 VCA26 = 0 VCA25 = 0 SVC0 = 1	While a WAIT instruction is executed Peripheral clock off	—	3.5	—	µA
		Stop mode	Off	Off	Off	Off	—	VCA27 = 0 VCA26 = 0 VCA25 = 0 CM10 = 1	Topr = 25°C Peripheral clock off	—	2.2	6	µA
			Off	Off	Off	Off	—	VCA27 = 0 VCA26 = 0 VCA25 = 0 CM10 = 1	Topr = 85°C Peripheral clock off	—	30	—	µA

Notes:
1. Vcc = 1.8 V to 2.7 V, single-chip mode, output pins are open, and other pins are Vss.
2. XIN is set to square wave input.
3. fHOCO-F
4. The typical value (Typ.) indicates the current value when the CPU and the memory operate.
   The maximum value (Max.) indicates the current value when the CPU, the memory, and the peripheral functions operate and the flash memory is programmed/erased.

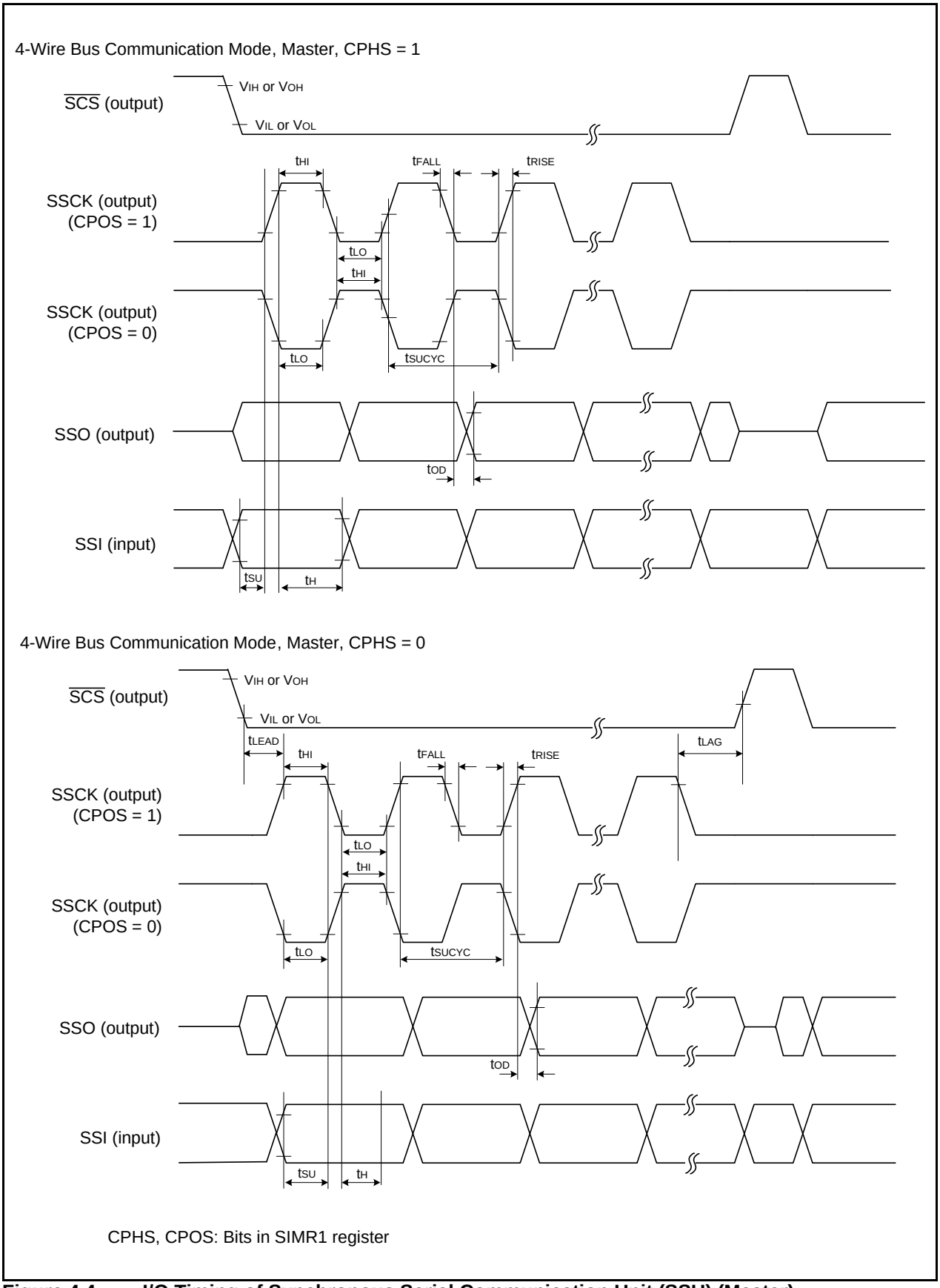


Figure 4.4 I/O Timing of Synchronous Serial Communication Unit (SSU) (Master)

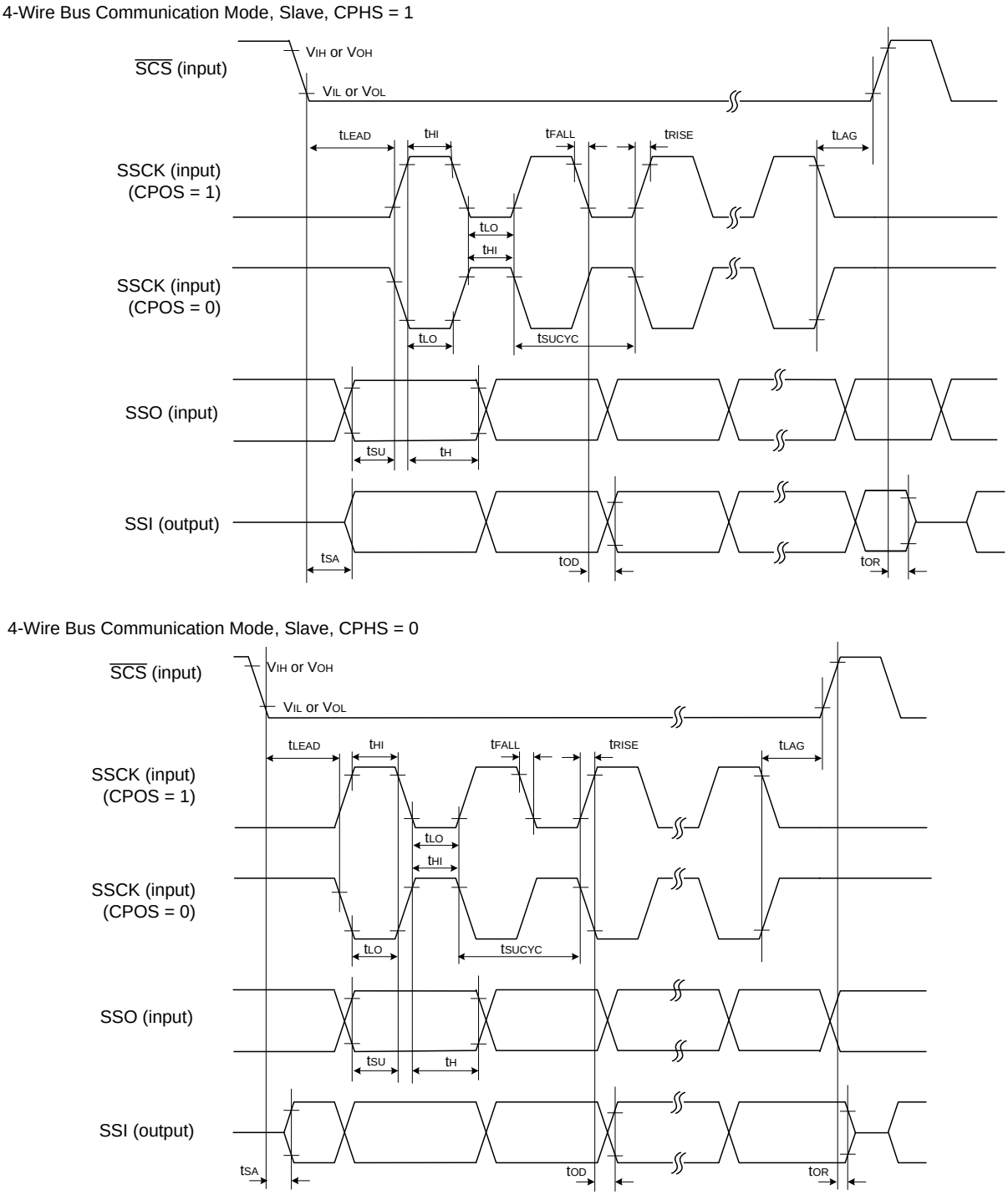


Figure 4.5 I/O Timing of Synchronous Serial Communication Unit (SSU) (Slave)

Table 4.24 Timing Requirements of Serial Interface (Internal clock selected as transfer clock (master communication))

Symbol	Parameter	Standard						Unit
		Vcc = 2.2 V, Topr = 25°C		Vcc = 3 V, Topr = 25°C		Vcc = 5 V, Topr = 25°C		
		Min.	Max.	Min.	Max.	Min.	Max.	
$t_{d(C-Q)}$	TXDi output delay time	—	200	—	30	—	10	ns
$t_{su(D-C)}$	RXDi input setup time (1)	150	—	120	—	90	—	ns
$t_{h(C-D)}$	RXDi input hold time	90	—	90	—	90	—	ns

i = 0 or 1

Note:

1. External pin load condition CL = 30 pF

Table 4.25 Timing Requirements of Serial Interface (External clock selected as transfer clock (slave communication))

Symbol	Parameter	Standard						Unit
		Vcc = 2.2 V, Topr = 25°C		Vcc = 3 V, Topr = 25°C		Vcc = 5 V, Topr = 25°C		
		Min.	Max.	Min.	Max.	Min.	Max.	
$t_{c(CK)}$	CLKi input cycle time	800	—	300	—	200	—	ns
$t_{w(CKH)}$	CLKi input high width	400	—	150	—	100	—	ns
$t_{w(CKL)}$	CLKi input low width	400	—	150	—	100	—	ns
$t_{d(C-Q)}$	TXDi output delay time	—	200	—	120	—	90	ns
$t_{su(D-C)}$	RXDi input setup time	150	—	30	—	10	—	ns
$t_{h(C-D)}$	RXDi input hold time	90	—	90	—	90	—	ns

i = 0 or 1

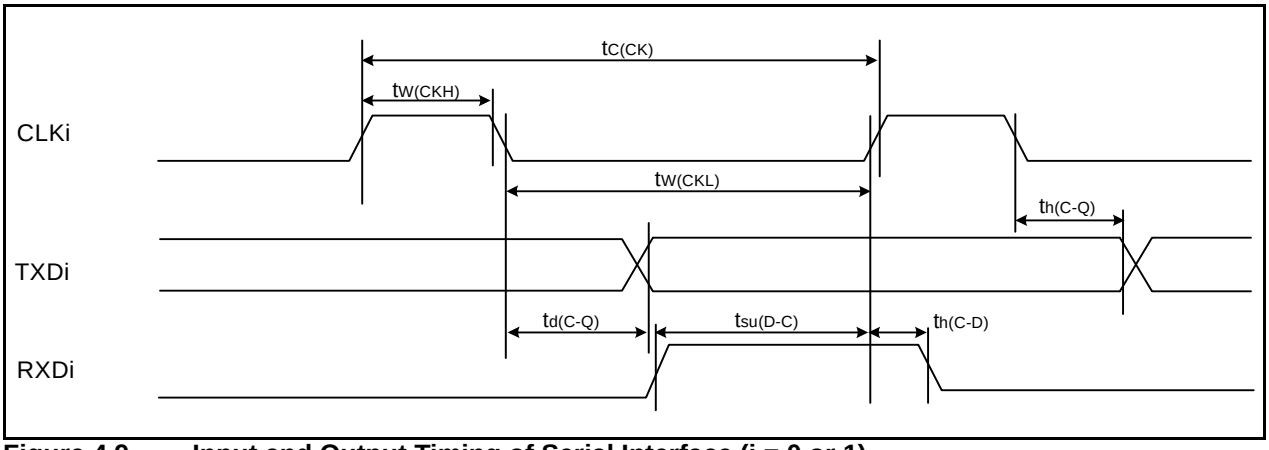
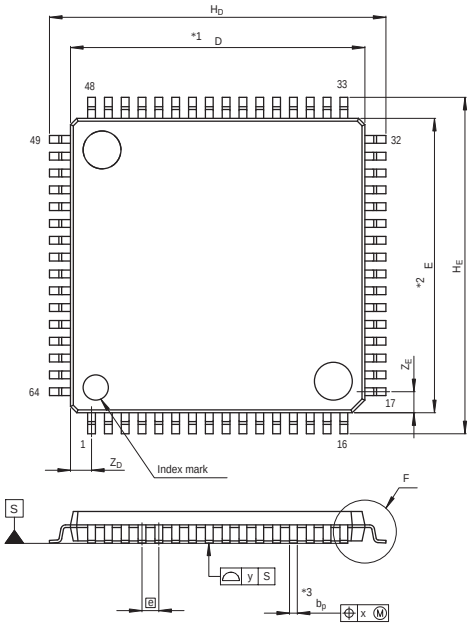
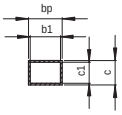


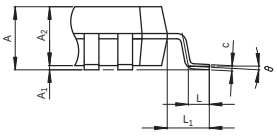
Figure 4.9 Input and Output Timing of Serial Interface (i = 0 or 1)

JEITA Package Code	RENESAS Code	Previous Code	MASS[Typ.]
P-LQFP64-14x14-0.80	PLQP0064GA-A	64P6U-A/ —	0.7g





Terminal cross section



Detail F

NOTE)
1. DIMENSIONS "*1" AND "*2" DO NOT INCLUDE MOLD FLASH.
2. DIMENSION "*3" DOES NOT INCLUDE TRIM OFFSET.

Reference Symbol	Dimension in Millimeters		
	Min	Nom	Max
D	13.9	14.0	14.1
E	13.9	14.0	14.1
A_2	—	1.4	—
H_D	15.8	16.0	16.2
H_E	15.8	16.0	16.2
A	—	—	1.7
A_1	0	0.1	0.2
b_p	0.32	0.37	0.42
b_1	—	0.35	—
c	0.09	0.145	0.20
c_1	—	0.125	—
θ	0°	—	8°
e	—	0.8	—
x	—	—	0.20
y	—	—	0.10
Z_D	—	1.0	—
Z_E	—	1.0	—
L	0.3	0.5	0.7
L_1	—	1.0	—

REVISION HISTORY	R8C/36T-A Group Datasheet

Rev.	Date	Description	
		Page	Summary
0.01	Feb 23, 2011	—	First Edition issued
1.00	Dec 09, 2011	All pages	“Preliminary”, “Under development” deleted, “sensor control unit” → “touch sensor control unit”
		2, 3	Tables 1.1 and 1.2 revised
		6	Figure 1.3 “P3_10/CH10” → “P3_1/CH10”
		11	Table 1.8 “Touch sensor control unit” added
		13	2.1 revised
		16, 17, 19 to 22, 24 to 28	Tables 3.1, 3.2, 3.4 to 3.7, 3.9 to 3.13
		32	Table 3.17 revised, Note 2 added
		33 to 56	“4. Electrical Characteristics” added

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Renesas Electronics America Inc.
2880 Scott Boulevard Santa Clara, CA 95050-2554, U.S.A.
Tel: +1-408-588-6000, Fax: +1-408-588-6130

Renesas Electronics Canada Limited
1101 Nicholson Road, Newmarket, Ontario L3Y 9C3, Canada
Tel: +1-905-898-5441, Fax: +1-905-898-3220

Renesas Electronics Europe Limited
Dukes Meadow, Millboard Road, Bourne End, Buckinghamshire, SL8 5FH, U.K
Tel: +44-1628-585-100, Fax: +44-1628-585-900

Renesas Electronics Europe GmbH
Arcadiastrasse 10, 40472 Düsseldorf, Germany
Tel: +49-211-65030, Fax: +49-211-6503-1327

Renesas Electronics (China) Co., Ltd.
7th Floor, Quantum Plaza, No.27 ZhiChunLu Haidian District, Beijing 100083, P.R.China
Tel: +86-10-8235-1155, Fax: +86-10-8235-7679

Renesas Electronics (Shanghai) Co., Ltd.
Unit 204, 205, AZIA Center, No.1233 Lujiazui Ring Rd., Pudong District, Shanghai 200120, China
Tel: +86-21-5877-1818, Fax: +86-21-6887-7858 / -7898

Renesas Electronics Hong Kong Limited
Unit 1601-1613, 16/F., Tower 2, Grand Century Place, 193 Prince Edward Road West, Mongkok, Kowloon, Hong Kong
Tel: +852-2886-9318, Fax: +852 2886-9022/9044

Renesas Electronics Taiwan Co., Ltd.
13F, No. 363, Fu Shing North Road, Taipei, Taiwan
Tel: +886-2-8175-9600, Fax: +886 2-8175-9670

Renesas Electronics Singapore Pte. Ltd.
1 harbourFront Avenue, #06-10, keppel Bay Tower, Singapore 098632
Tel: +65-6213-0200, Fax: +65-6278-8001

Renesas Electronics Malaysia Sdn.Bhd.
Unit 906, Block B, Menara Amcorp, Amcorp Trade Centre, No. 18, Jln Persiaran Barat, 46050 Petaling Jaya, Selangor Darul Ehsan, Malaysia
Tel: +60-3-7955-9390, Fax: +60-3-7955-9510

Renesas Electronics Korea Co., Ltd.
11F., Samik Lavied' or Bldg., 720-2 Yeoksam-Dong, Kangnam-Ku, Seoul 135-080, Korea
Tel: +82-2-558-3737, Fax: +82-2-558-5141

Colophon 1.1